Tyco Docket No. 18060 (20958-2113)

Via Facsimile Transmission 571.273.8300

Remarks

Claims 1, 2, 4-18 and 22-24 were pending in the present application, from which claims 10-18 had been withdrawn from consideration. By this amendment, claims 16-18 have been cancelled and new claims 25-27 have been added. It is respectfully submitted that the pending claims define allowable subject matter. No new subject matter has been introduced by the present amendment.

With respect to the rejection of claim 23 under 35 U.S.C § 112, first paragraph, it is believed that the above claim amendments overcome this rejection by more accurately stating that the actuator element moves the extractor block toward and away from the second surface of the circuit board and that the extractor block includes the extraction pins.

The Examiner is thanked for indicating claim 24 to be allowable. Accordingly, applicants have rewritten claim 24 in independent form.

With respect to the rejection of claims 1-2, 4-9 and 22 under 35 U.S.C. § 102(e) as being anticipated by Mimata et al (USP 6,505,397), it is still believed that claim 1 and the pending dependent claims are patentably distinct from the teachings and suggestions of Mimata. Accordingly, applicants respectfully traverse the rejection based on Mimata.

The claimed tool fundamentally differs from, and is intended for a different use than, the die holding mechanism of Mimata. Due to these fundamental differences, several elements of the structure of the claimed tool differ from the structure of Mimata's die holding mechanism. For example, Mimata's die holding mechanism is not intended for insertion and removal of an electrical connector onto and from a circuit board. Instead, Mimata's mechanism operates with a wafer sheet 6 having a series of dies 1 that are pasted onto the wafer sheet 6. Each die 1 has a series of wires 2 extending upward therefrom. The wires 2 do not extend into, nor join with, the wafer sheet 6. The wafer sheet 6 does not constitute a circuit board, nor do the dies 1 constitute connectors as claimed. Hence, numerous features of the claimed tool similarly differ from the structure of Mimata's die holding mechanism. For example, Mimata's die holding mechanism

entirely lacks an extraction mechanism that is configured to remove a connector from the surface of a circuit board.

Further, the dies 1 are not connectors and the wafer sheet 6 is not a circuit board. Therefore, the wafer suction holding body 11 does not teach or suggest the claimed extraction mechanism. Among other things, claim 1 requires an actuator that comprises a plurality of extraction pins that are configured to align with and extend into the pin aperture field in the